

Title (en)

METHOD OF OBTAINING A YELLOW GOLD ALLOY COATING BY ELECTROPLATING WITHOUT THE USE OF TOXIC METALS OR METALLOIDS

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ÜBERZUGS AUS GELBER GOLDLEGIERUNG DURCH GALVANISIEREN OHNE VERWENDUNG VON TOXISCHEN METALLEN ODER METALLOIDEN

Title (fr)

PROCÉDÉ D'OBTENTION D'UN DÉPÔT D'ALLIAGE D'OR JAUNE PAR GALVANOPLASTIE SANS UTILISATION DE MÉTAUX OU MÉTALLOÏDES TOXIQUES

Publication

**EP 2205778 B1 20110223 (FR)**

Application

**EP 08804009 A 20080911**

Priority

- EP 2008062042 W 20080911
- CH 14942007 A 20070921

Abstract (en)

[origin: US10619260B2] A galvanic bath, containing: gold metal in the form of alkaline aurocyanide; organometallic components; a wetting agent; a complexing agent; free cyanide; copper metal in the form of copper II cyanide and potassium; and indium metal in the form of a complex indium metal, where the galvanic bath does not contain cadmium and zinc, and where the galvanic bath deposits a yellow gold alloy comprising gold, copper, and indium as main components.

IPC 8 full level

**C25D 3/62** (2006.01)

CPC (source: EP US)

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